SKKT 215/18 E

SEMIPACK® 2

Thyristor Modules

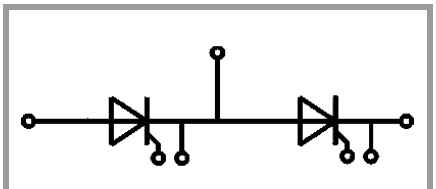
SKKT 215/18 E

Features

- Heat transfer through aluminium oxide ceramic insulated metal baseplate
- Hard soldered joints for high reliability
- UL recognized, file no. E63532

Typical Applications*

- DC motor control (e. g. for machine tools)
- AC motor soft starters
- Temperature control (e. g. for ovens, chemical processes)
- Professional light dimming (studios, theaters)



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Absolute Maximum Ratings				
Symbol	**Conditions**		**Values**	**Unit**
Chip				
$I_{T(AV)}$	sinus 180°	T_c = 85 °C	215	A
		T_c = 100 °C	153	A
I_{TSM}	10 ms	T_j = 25 °C	7000	A
		T_j = 125 °C	5700	A
i^2t	10 ms	T_j = 25 °C	245000	A^2s
		T_j = 125 °C	162450	A^2s
V_{RSM}			1900	V
V_{RRM}			1800	V
V_{DRM}			1800	V
$(di/dt)_{cr}$	T_j = 125 °C		200	A/µs
$(dv/dt)_{cr}$	T_j = 125 °C		1000	V/µs
T_j			-40 ... 125	°C
Module				
T_{stg}			-40 ... 125	°C
V_{isol}	a.c.; 50 Hz; r.m.s.	1 min	3000	V
		1 s	3600	V

Characteristics						
Symbol	**Conditions**		**min.**	**typ.**	**max.**	**Unit**
Chip						
V_T	T_j = 25 °C, I_T = 600 A				1.5	V
$V_{T(TO)}$	T_j = 125 °C				0.85	V
r_T	T_j = 125 °C				1.2	mΩ
I_{DD};I_{RD}	T_j = 125 °C, V_{DD} = V_{DRM}; V_{RD} = V_{RRM}				60	mA
t_{gd}	T_j = 25 °C, I_G = 1 A, di_G/dt = 1 A/µs			1		µs
t_{gr}	V_D = 0.67 * V_{DRM}			2		µs
t_q	T_j = 125 °C			150		µs
I_H	T_j = 25 °C			150	400	mA
I_L	T_j = 25 °C, R_G = 33 Ω			300	1000	mA
V_{GT}	T_j = 25 °C, d.c.		2			V
I_{GT}	T_j = 25 °C, d.c.		150			mA
V_{GD}	T_j = 125 °C, d.c.				0.25	V
I_{GD}	T_j = 125 °C, d.c.				10	mA
$R_{th(j-c)}$	cont.	per chip			0.12	K/W
		per module			0.06	K/W
$R_{th(j-c)}$	sin. 180°	per chip			0.125	K/W
		per module			0.065	K/W
$R_{th(j-c)}$	rec. 120°	per chip			0.14	K/W
		per module			0.07	K/W
Module						
$R_{th(c-s)}$	chip			0.04		K/W
	module			0.027		K/W
M_s	to heatsink M5		4.25		5.75	Nm
M_t	to terminals M6		4.25		5.75	Nm
a					5 * 9.81	m/s^2
w				165		g

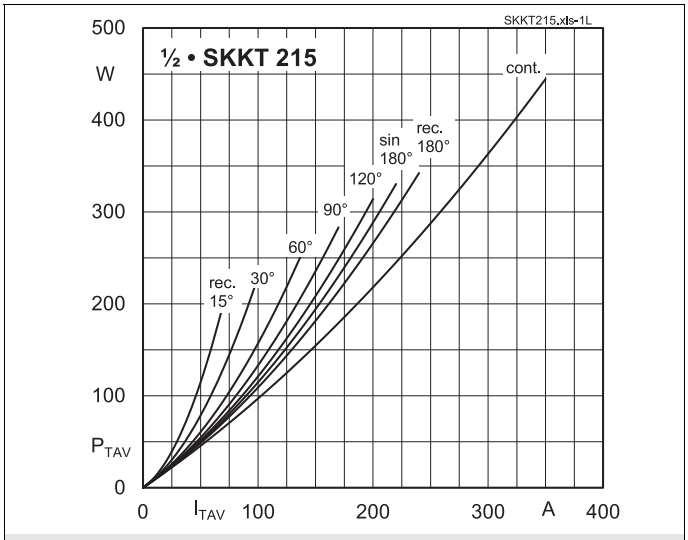


Fig. 1L: Power dissipation per thyristor vs. on-state current

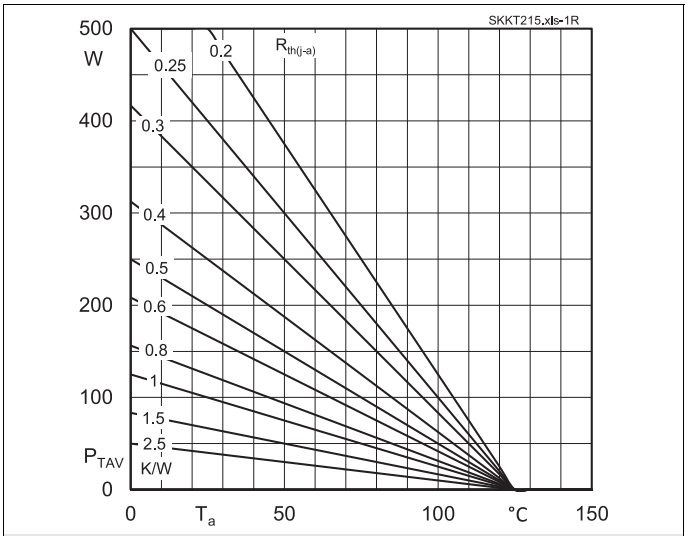


Fig. 1R: Max. power dissipation per chip vs. ambient temperature

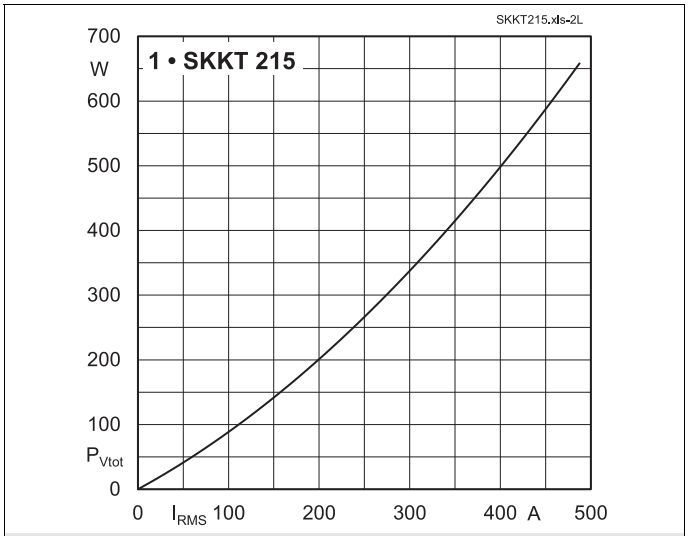


Fig. 2L: Max. power dissipation of one module vs. rms current

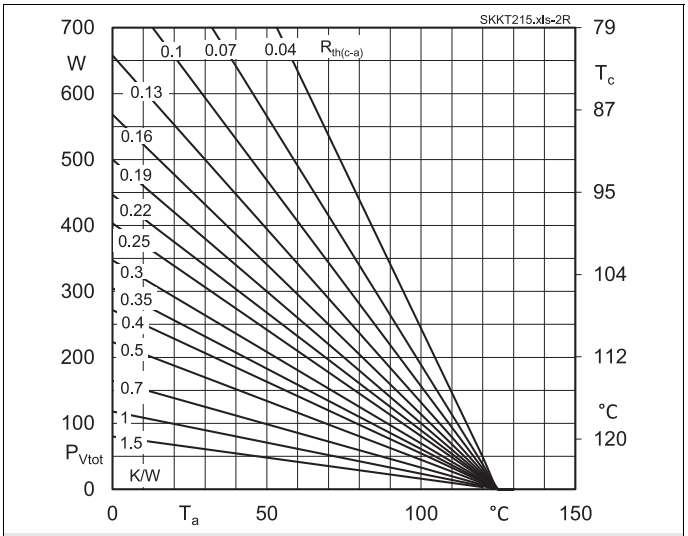


Fig. 2R: Max. power dissipation of one module vs. case temperature

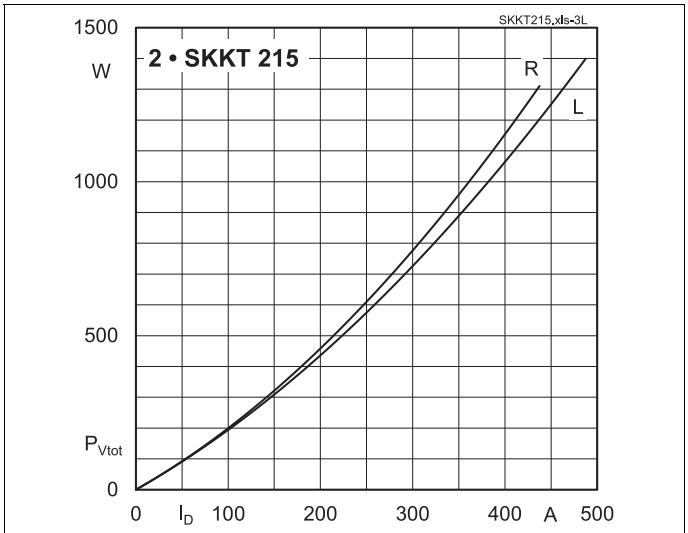


Fig. 3L: Max. power dissipation of two modules vs. direct current

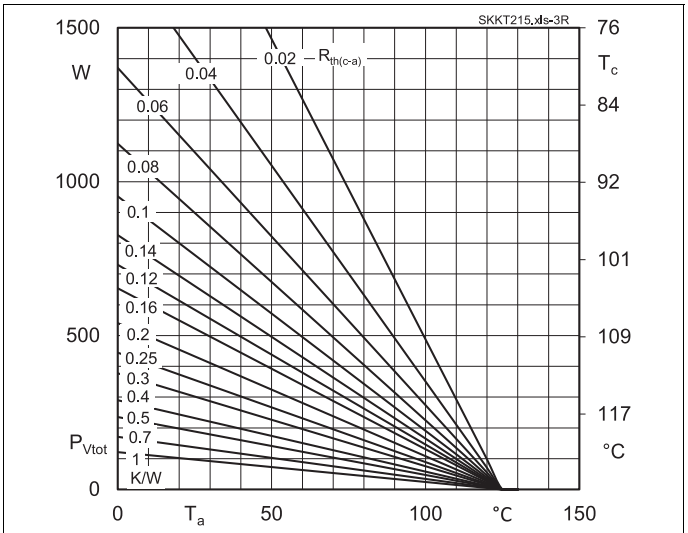


Fig. 3R: Max. power dissipation of two modules vs. case temperature

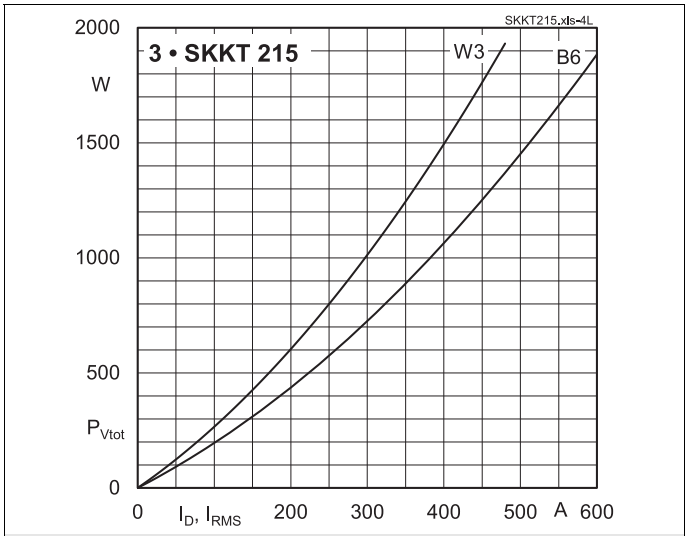


Fig. 4L: Max. power dissipation of three modules vs. direct current

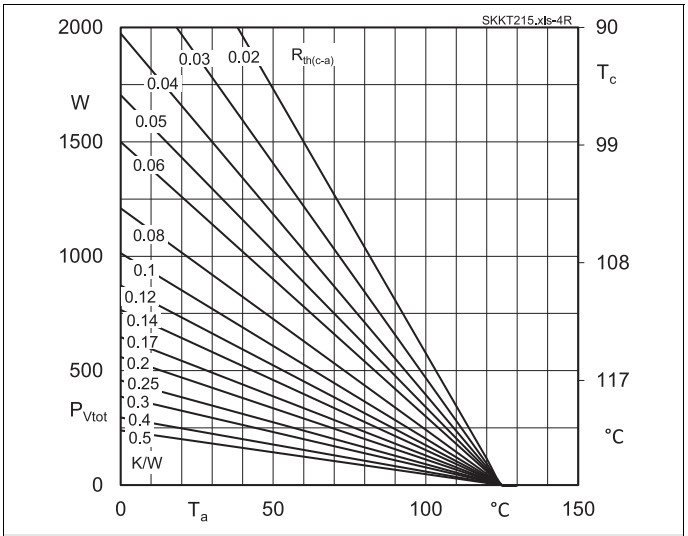


Fig. 4R: Max. power dissipation of three modules vs. case temperature

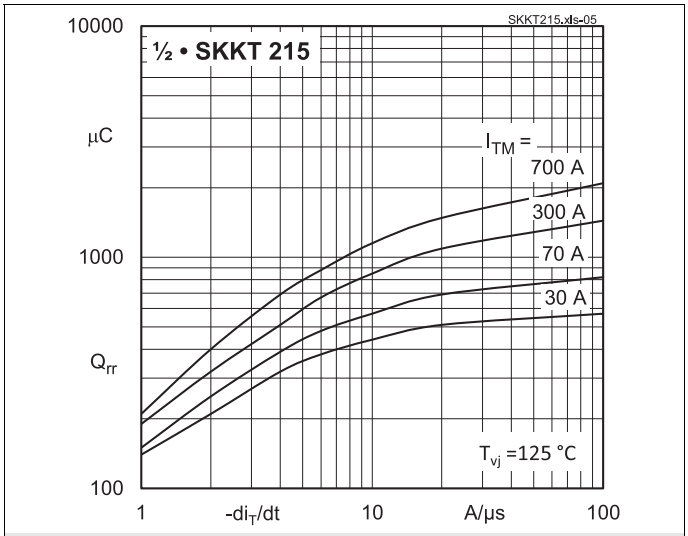


Fig. 5: Recovered charge vs. current decrease

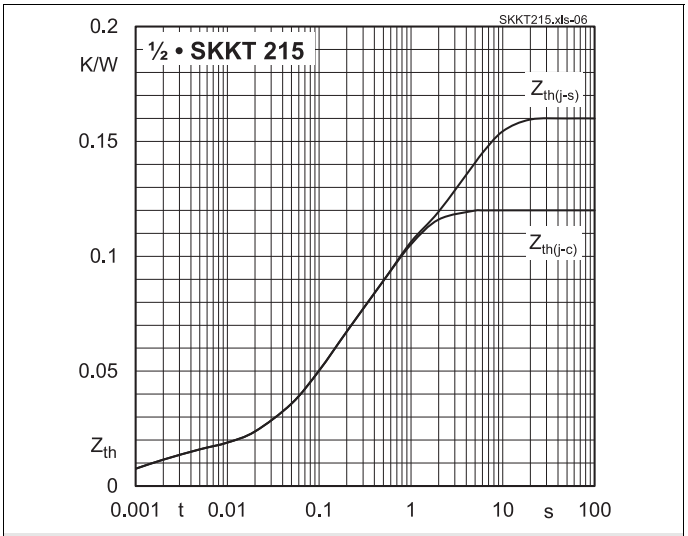


Fig. 6: Transient thermal impedance vs. time

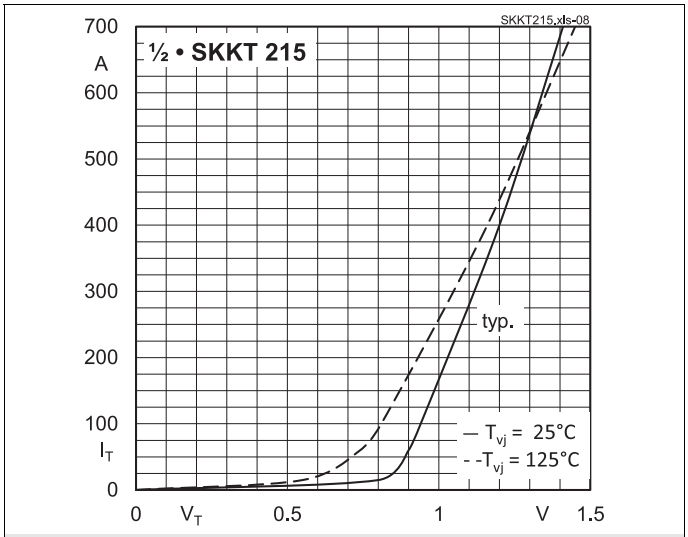


Fig. 7: On-state characteristics

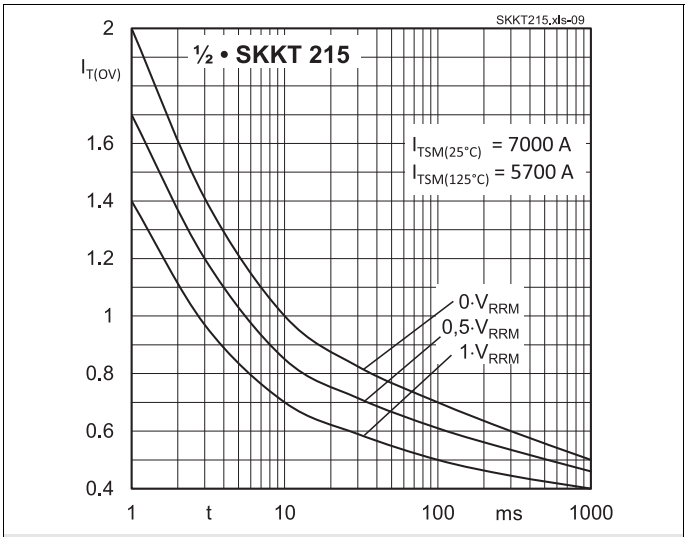


Fig. 8: Surge overload current vs. time

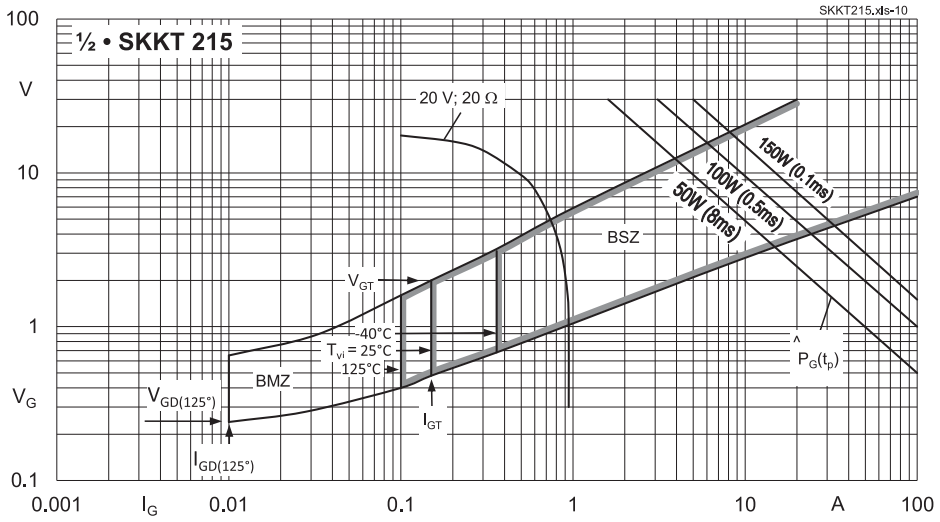
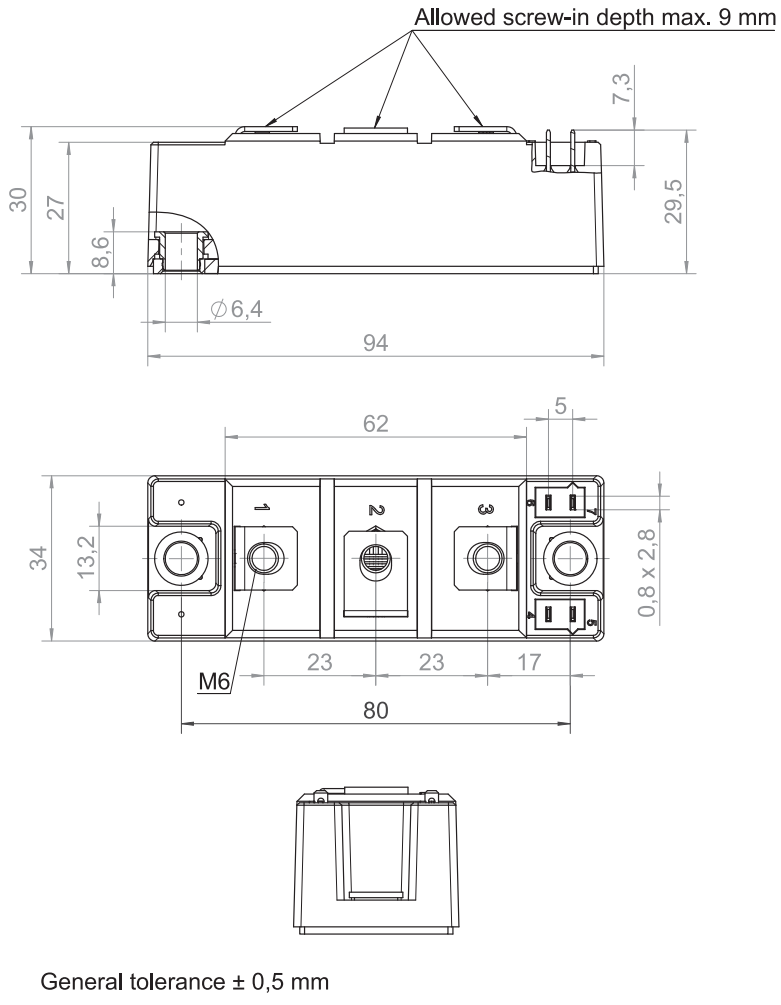


Fig. 9: Gate trigger characteristics



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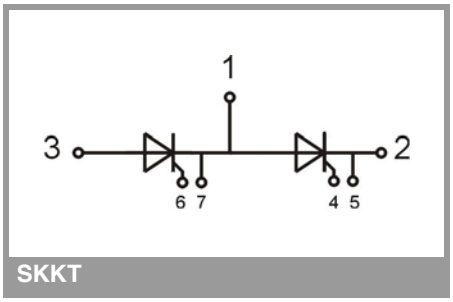

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This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, chapter IX.

***IMPORTANT INFORMATION AND WARNINGS**

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